

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims

1-12. (Canceled)

13. (Currently amended) A chemical mechanical polishing mixture, the mixture comprising:
a solution comprising:

an etchant selected from the group consisting of: a peroxide, a nitrate, a halogen-containing compound, a sulphate, a persulphate, an oxidizer, an inorganic acid or a salt thereof, and mixtures thereof, wherein the inorganic acid is selected from the group consisting of nitric acid, iodic acid, periodic acid, perbromic acid, perchloric acid and perboric acid;

a modifier; ~~and~~

a surfactant; and

a plurality of particles having an average particle diameter ranging from 500 to 2000 μm .

14. (Original) The mixture of claim 13 wherein a solution to void volume ratio is about one or less.

15. (Original) The mixture of claim 13 wherein the solution further comprises a solvent.

16. (Original) The mixture of claim 13 wherein the plurality of particles is contacted with the solution for a duration of at least 8 hours.

17. (Canceled)

18. (Original) The mixture of claim 13 wherein the modifier is at least one member selected from the group consisting of organic acids; amines; nitrogen-containing cyclic compounds; and combinations thereof.

19. (Currently amended) A chemical mechanical polishing mixture, the mixture comprising:
a solution comprising:

from about 0.1% to 20% by weight of an etchant selected from the group consisting of: a peroxide, a nitrate, a halogen-containing compound, a sulphate, a persulphate, an oxidizer, an inorganic acid or a salt thereof, and mixtures thereof, wherein the inorganic acid is selected from the group consisting of nitric acid, iodic acid, periodic acid, perbromic acid, perchloric acid and perboric acid;

0.1% to 15% by weight of a modifier;~~and~~

0.001% to 10% by weight of a surfactant;~~and~~

50 to 99% of a solvent; and

a plurality of particles with an average particle diameter ranging from 500 to 2000 μm ,
wherein a solution to void volume ratio is about one or less.

20. (Original) The mixture of claim 19 wherein the solution is contacted with the plurality of particles for at least 8 hours.

21. (Original) The mixture of claim 19 wherein the particles comprise non-abrasive particles.

22. (Original) The mixture of claim 19 wherein the particles are comprised of at least one member selected from the group consisting of aluminum oxide, silicon dioxide, silicon carbide, titanium oxide, magnesium oxide, zirconium oxide, porcelain, cerium oxide, and combinations thereof.

23. (Original) The mixture of claim 13 wherein the particles have an average particle diameter ranging from 500 to 2000 μm .

24. (Original) The mixture of claim 19 wherein the particles have an average particle diameter ranging from 500 to 2000 μm .